

**ABLESTIK 8008 MD**

January 2016

**PRODUCT DESCRIPTION**

LOCTITE ABLESTIK 8008MD provides the following product characteristics:

<b>Technology</b>	Proprietary Hybrid Chemistry
<b>Appearance</b>	Silver
<b>Cure</b>	Heat cure
<b>Product Benefits</b>	<ul style="list-style-type: none"><li>• Electrically conductive</li><li>• Thermally conductive</li><li>• Low modulus</li><li>• Good substrate wetting</li><li>• Controlled bondline thickness</li></ul>
<b>Application</b>	Die attach
<b>Filler Type</b>	Silver
<b>Substrates</b>	PPF, Copper and Silver-plated copper leadframes

LOCTITE ABLESTIK 8008MD adhesive is designed for medium die attach applications. This material can be applied to a wafer backside by stencil printing and then B-staged in an oven. The adhesive can then be cured after die attach in an in-line process. This material was originally released as RP-825-3C1.

**TYPICAL PROPERTIES OF UNCURED MATERIAL**

Thixotropic Index (0.5/5 rpm)	2.6
Viscosity, Brookfield CP51, 25 °C, mPa·s (cP): Speed 5 rpm	67,500
Work Life @ 25°C, hours	24
Shelf Life @ -40°C, days	365
Flash Point - See SDS	

**TYPICAL PROCESS DATA****Recommended B-Stage Condition**

10 minute ramp to 115°C + 60 minutes @ 115°C

**TYPICAL CURING PERFORMANCE****Recommended Cure Schedule**

30 minute ramp to 175°C + 60 minutes @ 175°C

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

**TYPICAL PROPERTIES OF CURED MATERIAL****Physical Properties**

Thermal Conductivity, W/(m-K)	6
Tensile Modulus, DMTA :	
@ -65 °C	N/mm <sup>2</sup> 7,702 (psi) (1,119,550)
@ 25 °C	N/mm <sup>2</sup> 3,880 (psi) (563,330)
@ 150 °C	N/mm <sup>2</sup> 1,050 (psi) (152,430)
@ 200 °C	N/mm <sup>2</sup> 630 (psi) (91,520)
@ 250 °C	N/mm <sup>2</sup> 440 (psi) (63,820)
Extractable Ionic Content, @ 100°C ppm:	
Chloride (Cl-)	<10
Sodium (Na+)	<10
Potassium (K+)	<10
Weight Loss @ 250°C, %	0.2

**Electrical Properties**

Volume Resistivity, ohms-cm	0.0005
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**TYPICAL PERFORMANCE OF CURED MATERIAL**

Die Shear Strength :

3 x 3 mm Si die on Different Leadframes, kg-f

Leadframe	@260°C
Ag/Cu Leadframe	2.7
Bare Cu Leadframe	2.5
Pd/Ni/Cu Leadframe	3

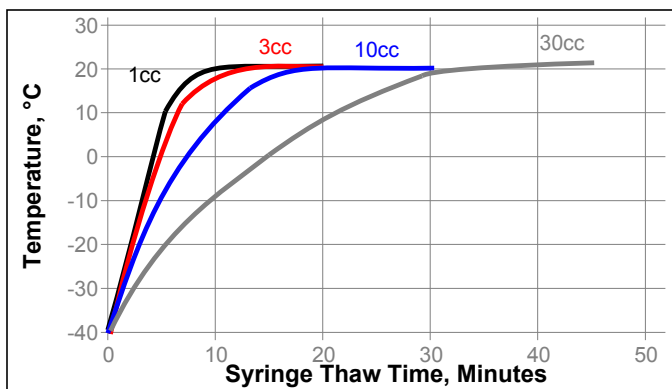
**GENERAL INFORMATION**

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

**THAWING:**

1. Allow container to reach room temperature before use.
2. After removing from the freezer, set the syringes to stand vertically while thawing.
3. Refer to the Syringe Thaw time chart for the thaw time recommendation.
4. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
5. DO NOT re-freeze. Once thawed to 25°C, the adhesive should not be re-frozen.





#### DIRECTIONS FOR USE

Apply enough adhesive to the stencil to ensure complete filling of the stencil with a 20 to 50 mm diameter bead. Typically, this requires 20 to 50 cc of adhesive depending on the stencil size. For two-direction printing, double beading is recommended.

#### NOTE:

Please refer to the Wafer Backside Coating Applications and Data Package for this product to review process windows and recommendations for each step.

#### Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

#### Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

**Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.**

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

#### Disclaimer

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